## Lesker PVD 200 RF Sputter STANDARD OPERATING PROCEDURE

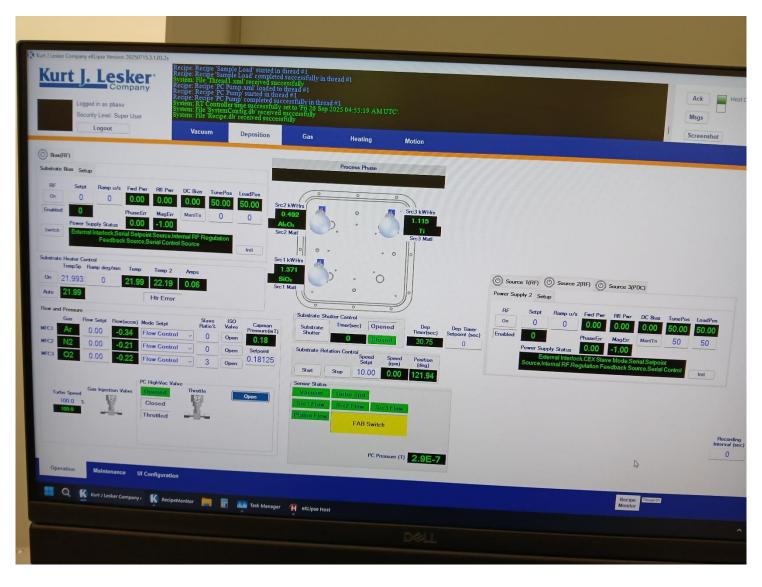
- 1. Start iLAB session.
- 2. Login with credentials on the top left of the screen.
- 3. The main GUI shows the PC Pressure as the chamber pressure in Torr. Users are suggested NOT to click anything on the main GUI "Vacuum" page.



4. Click "PC Vent" on the top right and wait for the chamber to vent to atmosphere.



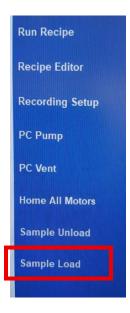
- 5. After the chamber pressure reaches atmosphere, the "PC Vent" recipe will be complete, and the user can open the main chamber door.
- 6. Click the "Deposition" Tab in the main GUI and the orientation of the three sputter guns are shown in the schematic below along with various other deposition parameters.
- 7. The numbering and arrangement of the sputter sources/guns as shown in the schematic below is same as in the actual main chamber. Src 1 means Source 1/ Gun 1; Src 2 means Source 2/Gun 2 and Src 3 means Source 3/Gun 3. Src 1 and Src 2 are RF sputter sources/guns and Src 3 is a DC sputter source/gun.



8. Click "Sample Unload" and the substrate holder will be brought down for unloading.



- 9. Once the "Sample Unload" recipe is completed as seen on the screen the substrate shutter will open, and all the sputtering gun shutters will also open. Users can physically unload the substrate holder from its slot to load their samples.
- 10. During this time users can also swap/load any sputtering target they brought from any source/gun and remove the Al foil from the sputtering source/gun they want to use.
- 11. After loading their samples, users can place the substrate holder in its slot and then click "Sample Load".



12. The substrate holder along with the sample will be raised and the substrate shutters and the sputter gun shutters will be closed and when the "Sample Load" recipe is complete, it will show on the screen.

13. Close the main chamber door and place the door latch in its slot and click "PC Pump".

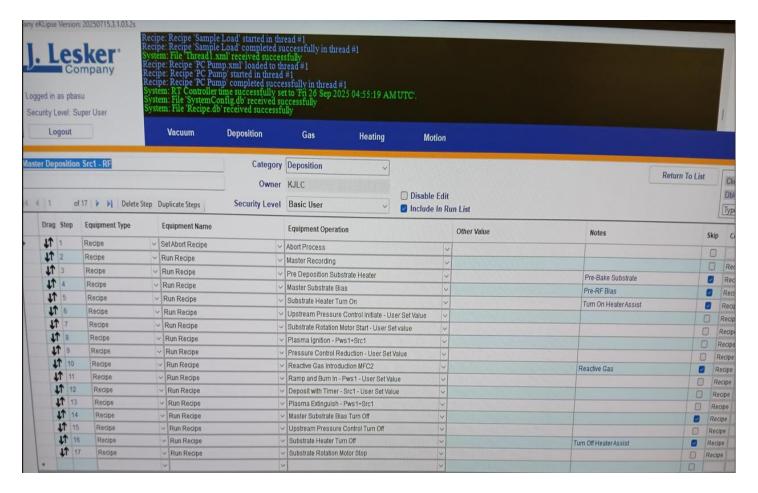


- 14. When the chamber pumps down, the door latch will automatically come off its slot.
- 15. Wait for the chamber PC Pressure (Base Pressure) to come down below 5E-6 Torr.
- 16. While the chamber is pumping down user can select "Recipe Editor".



- 17. After selecting "Recipe Editor" the page with all the process recipes will open. Users should always duplicate either Master Deposition Src 1- RF, Master Deposition Src 2- RF or Master Deposition Src 3- PDC depending on which source/gun they want to sputter from. Do NOT make edits/changes in any of these Master Deposition recipes.
- 18. After duplicating, users should rename the duplicated main recipe preferably with their name

19. Click View Recipe and the recipe details will open. The recipe details of Master Deposition Src 1-RF are shown below.

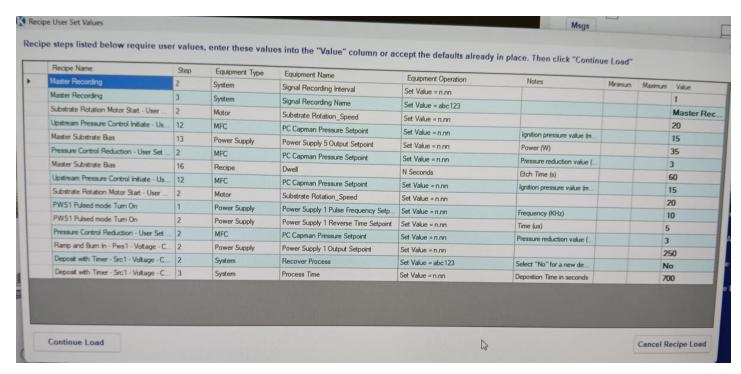


- 20. Each of the steps in this recipe are sub-recipes within the main Master Deposition recipe. They are basically accessed from the drop-down menu as shown in the above photo.
- 21. Users are requested to duplicate each of these sub recipe steps and rename them accordingly when they want to incorporate the sub recipe steps in their recipe. Do NOT make edits/ changes in the original sub recipes.
- 22. After duplicating the sub recipes and renaming them, users can change the process parameters within the respective sub recipe.
- 23. Users can incorporate their renamed sub recipes within their renamed main recipe from the drop-down menu as stated in step 20.
- 24. If users want to skip any sub recipe step, they can select Skip as shown in the right and that sub recipe step won't be executed while running the main recipe.

25. When the PC Pressure (Base Pressure) drops below 5E-6, click "Run Recipe".



26. After clicking "Run Recipe" this window will pop up as shown below. Users can make any final/additional changes on the recipe parameters in this window and then select Continue Load on the bottom left.



- 27. Once the recipe starts to run and sputter deposition begins, users should write down the relevant parameters under the "Deposition" Tab in the main GUI in the handwritten logbook.
- 28. After the recipe completes as seen on the screen, click "PC Vent".
- Once the chamber reaches atmosphere and the PC Vent recipe completes, open the main chamber door.
- 30. Click "Sample Unload" and the substrate holder will be brought down for unloading.

- 31. Once the "Sample Unload" recipe is completed as seen on the screen the substrate shutter will open, and all the sputtering gun shutters will also open. Users can physically unload the substrate holder from its slot to unload their samples.
- 32. During this time users should unload any target they installed in any of the guns and make sure the sputtering gun is reassembled with the Al foil on the sputtering gun. If they swapped any Aggiefab provided target with their own target they should ensure that the Aggiefab provided target is reinstalled and they take their own target back with them.
- 33. After unloading the sample from the substrate holder, place the substrate holder in its slot and then click "Sample Load".
- 34. The substrate holder along with the sample will be raised and the substrate shutters and the sputter gun shutters will be closed and when the "Sample Load" recipe is complete, it will show on the screen.
- 35. Close the main chamber door and place the door latch in its slot and click "PC Pump".
- 36. When the chamber pumps down, the door latch will automatically come off its slot.
- 37. Log out from the tool.
- 38. End iLAB session.

## SIGNATURES AND REVISION HISTORY

a. Author of this document: Prithvi Basub. Author Title or Role: Research Engineer

c. Date: 10/13/2025

d. Revision: Original Issue

## Approvals:

Technical Manager Signature: Sandra G Malhotra

Date: 10/14/2025

## **Revision History:**

Revision	Author	Date
Original Issue for new tool	Prithvi Basu	10/13/2025
Rev A		
Rev B		
Rev C		